

Method for Coating Cavities of a Semiconductor Substrate

Abstract

This invention relates to a method for temporary coating of cavities (2), which at least partially run through a semiconductor substrate (1) and are provided for a permanent coating and/or equipping, with a temporarily applied coating material (3) before processing steps for processing at least one surface (1o) of the semiconductor substrate (1).

In addition, the invention relates to a method for removing a temporary coating of cavities (2) of a semiconductor substrate (1), whereby the coating is applied according to a previously-mentioned method and whereby, in particular immediately afterwards, a permanent coating and/or equipping of the cavities (2) is carried out.

In this regard, see Figure 3.